Ultra Series™ Crystal Oscillator
Si560 Data Sheet

Ultra Low Jitter Any-Frequency XO (90 fs), 0.2 to 3000 MHz

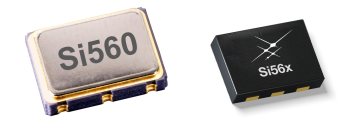
The Si560 Ultra Series™ oscillator utilizes Skyworks Solutions' advanced 4th generation DSPLL® technology to provide an ultra-low jitter, low phase noise clock at any output frequency. The device is factory-programmed to any frequency from 0.2 to 3000 MHz with <1 ppb resolution and maintains exceptionally low jitter for both integer and fractional frequencies across its operating range. The Si560 offers excellent reliability and frequency stability as well as guaranteed aging performance. On-chip power supply filtering provides industry-leading power supply noise rejection, simplifying the task of generating low jitter clocks in noisy systems that use switched-mode power supplies. Offered in industry-standard footprints, the Si560 has a dramatically simplified supply chain that enables Skyworks to ship custom frequency samples 1-2 weeks after receipt of order. Unlike a traditional XO, where a different crystal is required for each output frequency, the Si560 uses one simple crystal and a DSPLL IC-based approach to provide the desired output frequency. This process also guarantees 100% electrical testing of every device. The Si560 is factory-configurable for a wide variety of user specifications, including frequency, output format, and OE pin location/polarity. Specific configurations are factory-programmed at time of shipment, eliminating the long lead times associated with custom oscillators.

KEY FEATURES

- Available with any frequency from 0.2 MHz to 3000 MHz
- Ultra low jitter: 90 fs RMS typical (12 kHz – 20 MHz)
- Excellent PSNR and supply noise immunity: –80 dBc Typ
- 20 ppm temp stability (–40 to 85 °C)
- 3.3 V, 2.5 V and 1.8 V V_{DD} supply operation from the same part number
- LVPECL, LVDS, CML, HCSL, CMOS, and Dual CMOS output options
- 2.5x3.2, 3.2x5, 7x7 mm package options
- Samples available with 1-2 week lead times

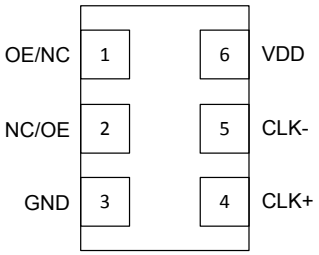
APPLICATIONS

- 100G/200G/400G OTN, coherent optics
- 10G/40G/100G optical ethernet
- 56G/112G PAM4 clocking
- 3G-SDI/12G-SDI/24G-SDI broadcast video
- Datacenter
- Test and measurement
- FPGA/ASIC clocking



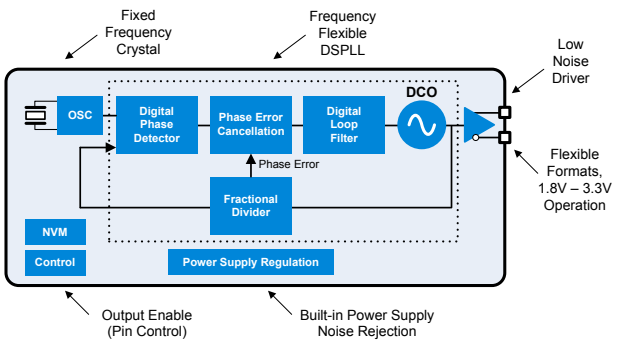
5 x 7 mm and 3.2 x 5 mm 2.5 x 3.2 mm

Pin Assignments



(Top View)

Pin #	Descriptions
1, 2	*Selectable via ordering option* OE = Output enable; NC = No connect
3	GND = Ground
4	CLK+ = Clock output
5	CLK- = Complementary clock output. Not used for CMOS.
6	VDD = Power supply



1. Ordering Guide

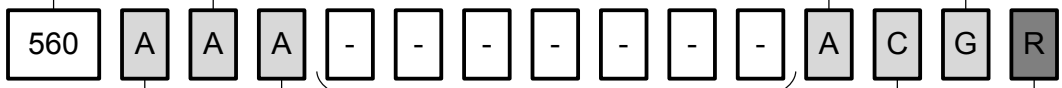
The Si560 XO supports a variety of options including frequency, output format, and OE pin location/polarity, as shown in the chart below. Specific device configurations are programmed into the part at time of shipment, and samples are available in 1-2 weeks. Skyworks Solutions provides an online part number configuration utility to simplify this process. Refer to https://www.skyworksinc.com/en/Products/Timing-Oscillators to access this tool and for further ordering instructions.

XO Series	Description
560	Single Frequency

	Temp Stability	Total Stability[2]
A	± 20 ppm	± 50 ppm

	Package
A	5x7 mm
B	3.2x5 mm
C	2.5x3.2 mm

	Temperature Grade
G	-40 to 85 °C



Device Revision

Signal Format	VDD Range	Order Option
LVPECL	2.5, 3.3 V	A
LVDS	1.8, 2.5, 3.3 V	B
CMOS	1.8, 2.5, 3.3 V	C
CML	1.8, 2.5, 3.3 V	D
HCSL	1.8, 2.5, 3.3 V	E
Dual CMOS (In-Phase)	1.8, 2.5, 3.3 V	F
Dual CMOS (Complementary)	1.8, 2.5, 3.3 V	G
HCSL-Fast	1.8, 2.5, 3.3 V	H
Custom	1.8, 2.5, 3.3 V	X

	OE Pin	OE Polarity
A	Pin 1	Active High
B	Pin 1	Active Low
C	Pin 2	Active High
D	Pin 2	Active Low

	Reel
R	Tape and Reel
<Blank>	Coil Tape

Frequency Code[3]	Description
Mxxxxxx	F_{CLK} < 1 MHz
xMxxxxx	1 MHz ≤ F_{CLK} < 10 MHz
xxMxxxx	10 MHz ≤ F_{CLK} < 100 MHz
xxxMxxx	100 MHz ≤ F_{CLK} < 1000 MHz
xxxxMxx	1000 MHz ≤ F_{CLK} ≤ 3000 MHz
xxxxxx	Custom code if F_{CLK} > 6 digits

Notes:

1. Contact Skyworks for non-standard configurations.
2. Total stability includes temp stability, initial accuracy, load pulling, VDD variation, and 20 year aging at 70 °C.
3. For example: 156.25 MHz = 156M250; 25 MHz = 25M0000. Create custom part numbers at https://www.skyworksinc.com/en/Products/Timing-Oscillators.

1.1 Technical Support

Oscillator Phase Noise Lookup Utility	https://www.skyworksinc.com/tools/oscillator-phase-noise
Quality and Reliability	https://www.skyworksinc.com/quality
Development Kits	https://www.skyworksinc.com/en/Products/Timing

2. Electrical Specifications

Table 2.1. Electrical Specifications

V_{DD} = 1.8 V, 2.5 or 3.3 V ± 5%, T_A = –40 to 85 ºC

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Temperature Range	T_A		–40	—	85	ºC
Frequency Range	F_{CLK}	LVPECL, LVDS, CML	0.2	—	3000	MHz
		HCSL	0.2	—	400	MHz
		CMOS, Dual CMOS	0.2	—	250	MHz
Supply Voltage	V_{DD}	3.3 V	3.135	3.3	3.465	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
Supply Current	I_{DD}	LVPECL (output enabled)	—	110	160	mA
		LVDS/CML (output enabled)	—	90	130	mA
		HCSL (output enabled)	—	85	130	mA
		HCSL-Fast (output enabled)	—	93	142	mA
		CMOS (output enabled)	—	85	135	mA
		Dual CMOS (output enabled)	—	95	145	mA
		Tristate Hi-Z (output disabled)	—	73	—	mA
Temperature Stability		Frequency stability Grade A	–20	—	20	ppm
Total Stability[1]	F_{STAB}	Frequency stability Grade A	–50	—	50	ppm
Rise/Fall Time (20% to 80% V_{PP})	T_R/T_F	LVPECL/LVDS/CML	—	—	350	ps
		CMOS / Dual CMOS, (C_L = 5 pF)	—	0.5	1.5	ns
		HCSL, F_{CLK} >50 MHz	—	—	550	ps
		HCSL-Fast, F_{CLK} >50 MHz	—	—	275	ps
Duty Cycle	D_C	All formats	45	—	55	%
Output Enable (OE)[2]	V_{IH}		0.7 × V_{DD}	—	—	V
	V_{IL}		—	—	0.3 × V_{DD}	V
	T_D	Output Disable Time, F_{CLK} > 10 MHz	—	—	3	µs
	T_E	Output Enable Time, F_{CLK} > 10 MHz	—	—	20	µs
Powerup Time	t_{OSC}	Time from 0.9 × V_{DD} until output frequency (F_{CLK}) within spec	—	—	10	ms
Powerup VDD Ramp Rate	V_{RAMP}	Fastest V_{DD} ramp rate allowed on startup	—	—	100	V/ms
LVPECL Output Option[3]	V_{OC}	Mid-level	V_{DD} – 1.42	—	V_{DD} – 1.25	V
	V_O	Swing (diff, $F_{CLK} \leq$ 1.5 GHz)	1.1	—	1.9	V_{PP}
		Swing (diff, F_{CLK} > 1.5 GHz)[6]	0.55	—	1.7	V_{PP}

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
LVDS Output Option[4]	V_{OC}	Mid-level (2.5 V, 3.3 V VDD)	1.125	1.20	1.275	V
		Mid-level (1.8 V VDD)	0.8	0.9	1.0	V
	V_O	Swing (diff, $F_{CLK} \leq$ 1.4 GHz)	0.6	0.7	0.9	V_{PP}
		Swing (diff, F_{CLK} > 1.4 GHz) [6]	0.25	0.5	0.8	V_{PP}
HCSL Output Option[5] HCSL-Fast Output Option [5]	V_{OH}	Output voltage high	660	800	850	mV
	V_{OL}	Output voltage low	–150	0	150	mV
	V_C	Crossing voltage	250	410	550	mV
CML Output Option (AC-Coupled)	V_O	Swing (diff, $F_{CLK} \leq$ 1.5 GHz)	0.6	0.8	1.0	V_{PP}
		Swing (diff, F_{CLK} > 1.5 GHz)[6]	0.3	0.55	0.9	V_{PP}
CMOS Output Option	V_{OH}	I_{OH} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	0.85 × V_{DD}	—	—	V
	V_{OL}	I_{OL} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	—	—	0.15 × V_{DD}	V

Notes:

1. Total Stability includes temperature stability, initial accuracy, load pulling, VDD variation, and aging for 20 yrs at 70 ºC.
2. OE includes a 50 kΩ pull-up to VDD for OE active high, or includes a 50 kΩ pull-down to GND for OE active low.
3. R_{term} = 50 Ω to V_{DD} – 2.0 V (see Figure 4.1). Additional DC current from the output driver will flow through the 50 Ω resistors, resulting in a shift in common mode voltage. The measurements in this table have accounted for this.
4. R_{term} = 100 Ω (differential) (see Figure 4.2).
5. R_{term} = 50 Ω to GND (see Figure 4.2).
6. Refer to the figure below for Typical Clock Output Swing Amplitudes vs Frequency.

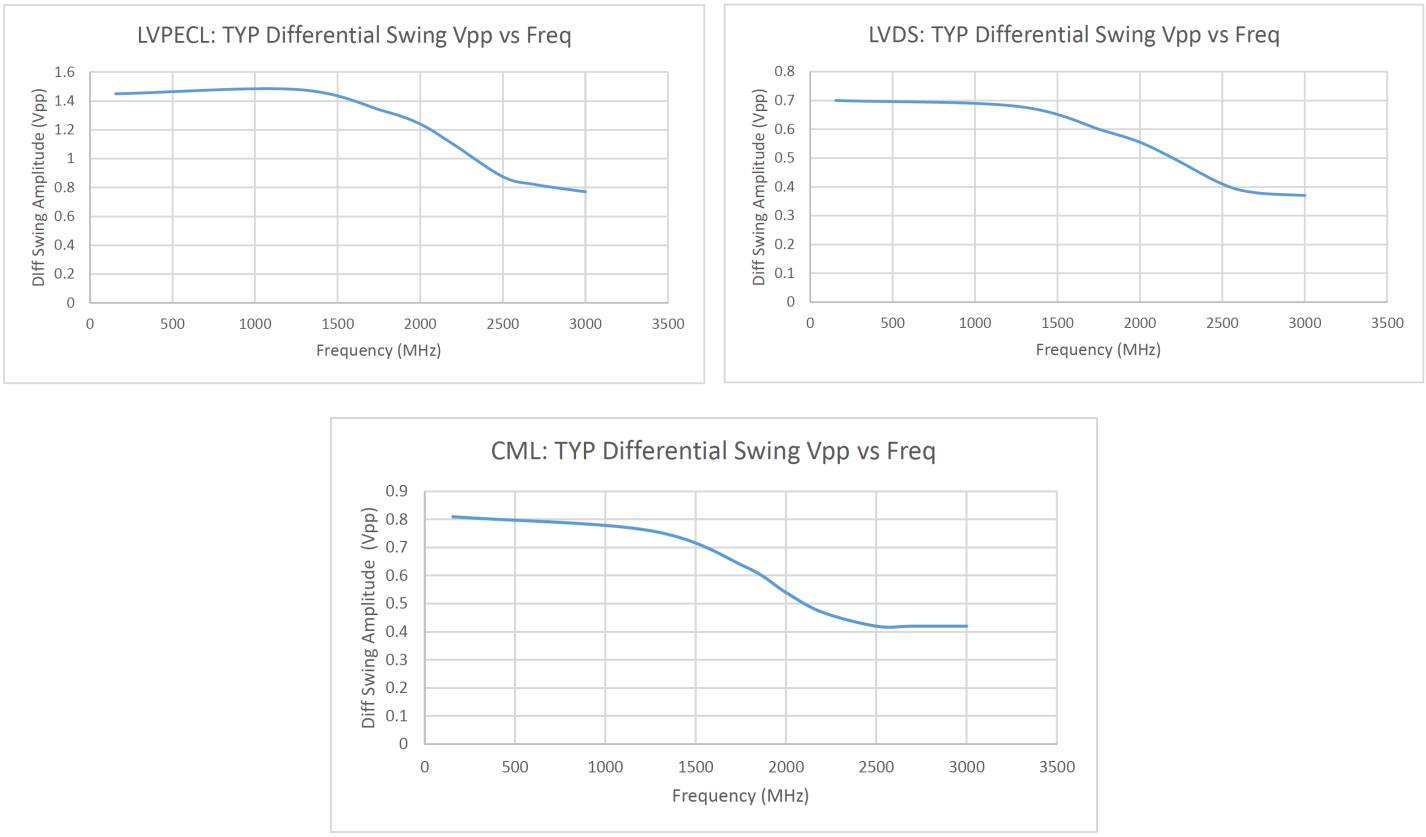


Figure 2.1. Typical Clock Output Swing Amplitudes vs. Frequency

Table 2.2. Clock Output Phase Jitter and PSNR

V_{DD} = 1.8 V, 2.5 or 3.3 V ± 5%, T_A = –40 to 85 ºC

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Phase Jitter (RMS, 12 kHz - 20 MHz)[1] All Differential Formats	ϕJ	F_{CLK} ≥ 200 MHz	—	90	140	fs
		100 MHz ≤ F_{CLK} < 200 MHz	—	105	160	fs
		LVPECL @ 156.25 MHz	—	95	135	fs
Phase Jitter (RMS, 12 kHz - 20 MHz)[1] CMOS / Dual CMOS Formats	ϕJ	10 MHz ≤ F_{CLK} < 250 MHz	—	200	—	fs
Spurs Induced by External Power Supply Noise, 50 mVpp Ripple. LVDS 156.25 MHz Output	PSNR	100 kHz sine wave		-83		dBc
		200 kHz sine wave		-83		
		500 kHz sine wave		-82		
		1 MHz sine wave		-85		

Note:

1. Guaranteed by characterization. Jitter inclusive of any spurs.

Table 2.3. 3.2 x 5 mm Clock Output Phase Noise (Typical)

Offset Frequency (f)	156.25 MHz LVDS	200 MHz LVDS	644.53125 MHz LVDS	Unit
100 Hz	–105	–100	–92	dBc/Hz
1 kHz	–129	–126	–116	
10 kHz	–136	–133	–125	
100 kHz	–142	–140	–131	
1 MHz	–150	–148	–138	
10 MHz	–159	–161	–153	
20 MHz	–160	–162	–154	
Offset Frequency (f)	**156.25 MHz LVPECL**	**200 MHz LVPECL**	**644.53125 MHz LVPECL**	**Unit**
100 Hz	–109	–102	–92	dBc/Hz
1 kHz	–131	–126	–119	
10 kHz	–135	–134	–124	
100 kHz	–143	–141	–130	
1 MHz	–150	–148	–138	
10 MHz	–160	–162	–154	
20 MHz	–161	–163	–155	

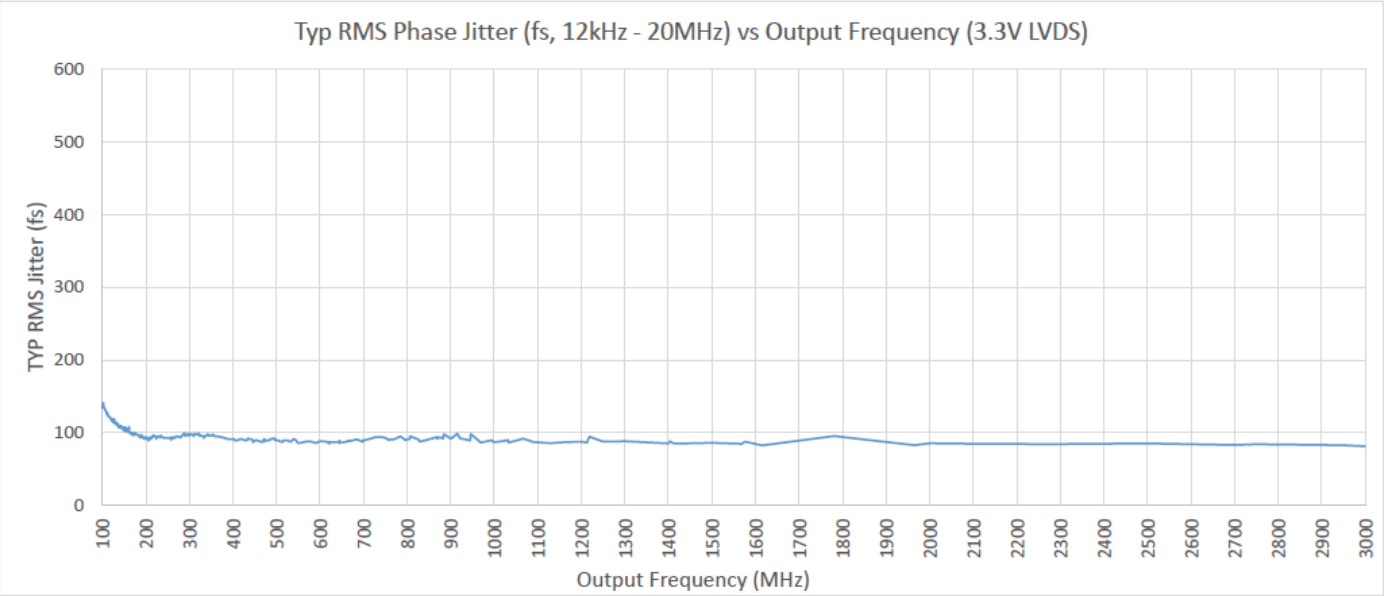


Figure 2.2. Phase Jitter vs. Output Frequency

Phase jitter measured with Agilent E5052 using a differential-to-single ended converter (balun or buffer). Measurements collected for >700 commonly used frequencies. Phase noise plots for specific frequencies are available using our free, online Oscillator Phase Noise Lookup Tool at www.silabs.com/oscillators.

Table 2.4. Environmental Compliance and Package Information

Parameter	Test Condition
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level (MSL): 3.2 x 5, 5 x 7 packages	1
Moisture Sensitivity Level (MSL): 2.5 x 3.2 package	2
Contact Pads: 3.2x5, 5x7 packages	Au/Ni (0.3 - 1.0 µm / 1.27 - 8.89 µm)
Contact Pads: 2.5x3.2 packages	Au/Pd/Ni (0.03 - 0.12 µm / 0.1 - 0.2 µm / 3.0 - 8.0 µm)

Note:

1. For additional product information not listed in the data sheet (e.g. RoHS Certifications, MDDS data, qualification data, REACH Declarations, ECCN codes, etc.), refer to our "Corporate Request For Information" portal found here: www.skyworksinc.com/quality.

Table 2.5. Thermal Conditions[1]

Max Junction Temperature = 125° C

Package	Parameter	Symbol	Test Condition	Value	Unit
2.5 x 3.2 mm 6-pin DFN[2]	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	72	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	38	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	15	°C/W
3.2 × 5 mm 6-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	55	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	20	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	20	°C/W
5 × 7 mm 6-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	53	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	26	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	26	°C/W

Note:

1. Based on PCB Dimensions: 4.5" x 7", PCB Thickness: 1.6 mm, Number of Cu Layers: 4.
2. For best 2.5x3.2mm thermal performance, use 2 GND vias as shown in the Si5xxUC-EVB eval board layout

Table 2.6. Absolute Maximum Ratings[1]

Parameter	Symbol	Rating	Unit
Maximum Operating Temp.	T_{AMAX}	95	ºC
Storage Temperature	T_S	–55 to 125	ºC
Supply Voltage	V_{DD}	–0.5 to 3.8	ºC
Input Voltage	V_{IN}	–0.5 to V_{DD} + 0.3	V
ESD HBM (JESD22-A114)	HBM	2.0	kV
Solder Temperature[2]	T_{PEAK}	260	ºC
Solder Time at T_{PEAK}[2]	T_P	20–40	sec

Notes:

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020.

3. Dual CMOS Buffer

Dual CMOS output format ordering options support either complementary or in-phase signals for two identical frequency outputs. This feature enables replacement of multiple XOs with a single Si560 device.

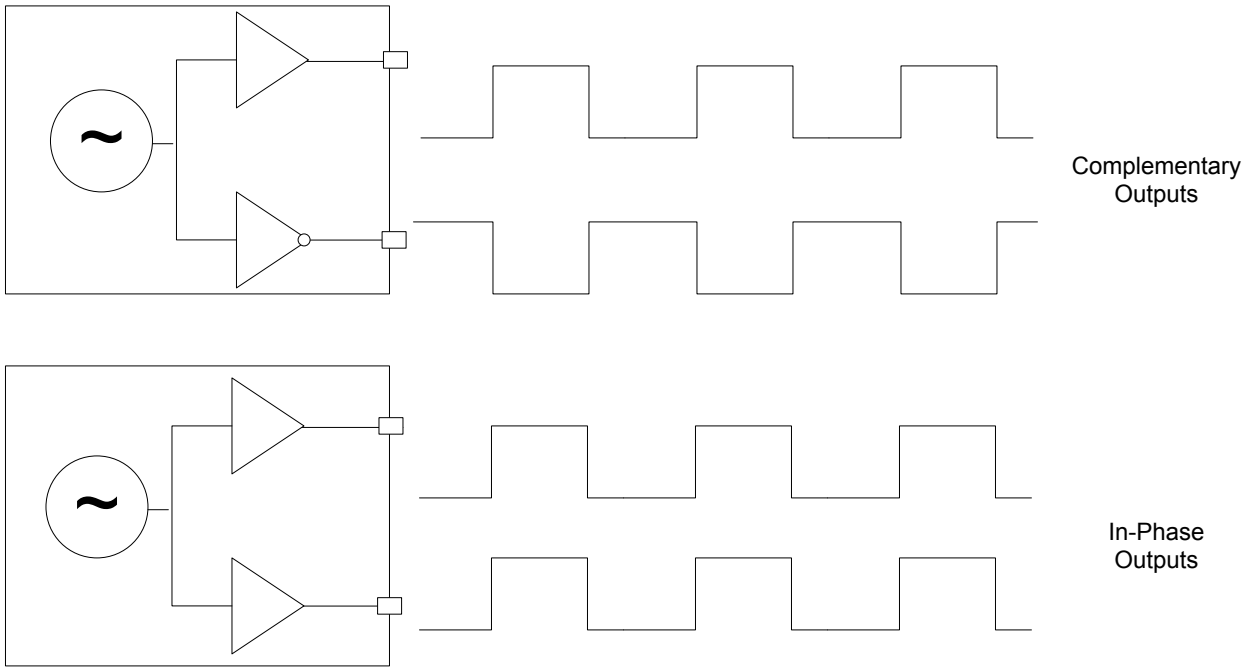


Figure 3.1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Outputs

4. Recommended Output Terminations

The output drivers support both AC-coupled and DC-coupled terminations as shown in figures below.

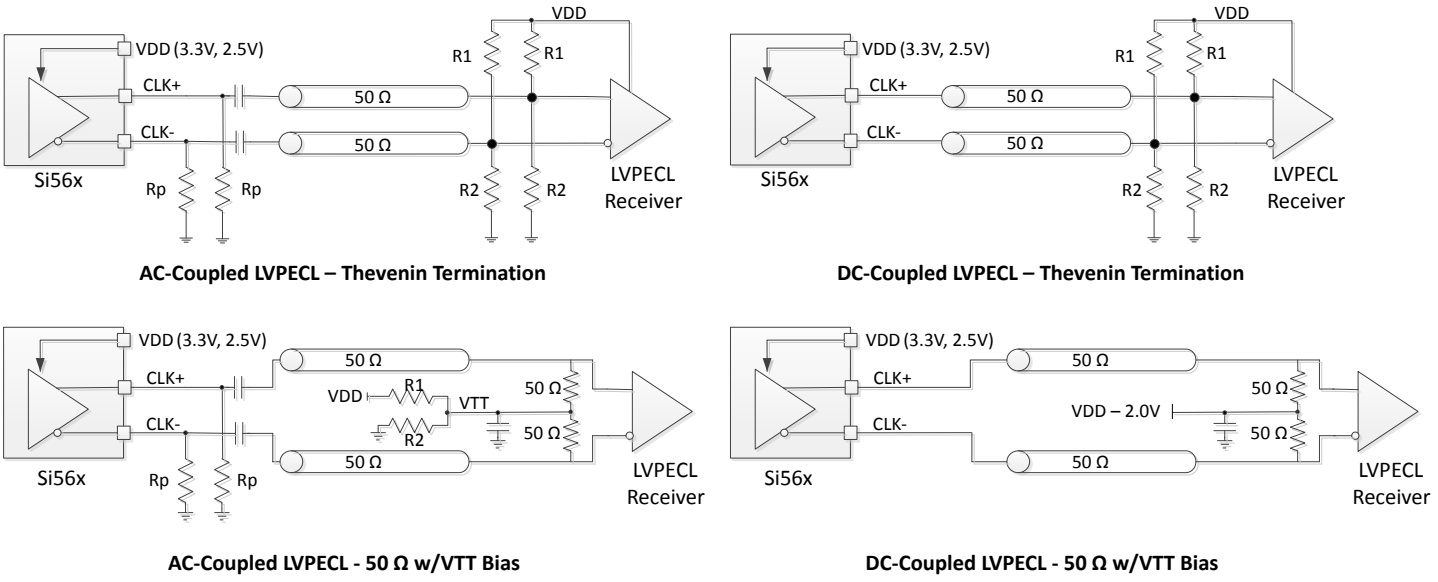


Figure 4.1. LVPECL Output Terminations

AC-Coupled LVPECL Termination Resistor Values			
VDD	R1	R2	Rp
3.3 V	82.5 Ω	127 Ω	130 Ω
2.5 V	62.5 Ω	250 Ω	90 Ω

DC-Coupled LVPECL Termination Resistor Values		
VDD	R1	R2
3.3 V	127 Ω	82.5 Ω
2.5 V	250 Ω	62.5 Ω

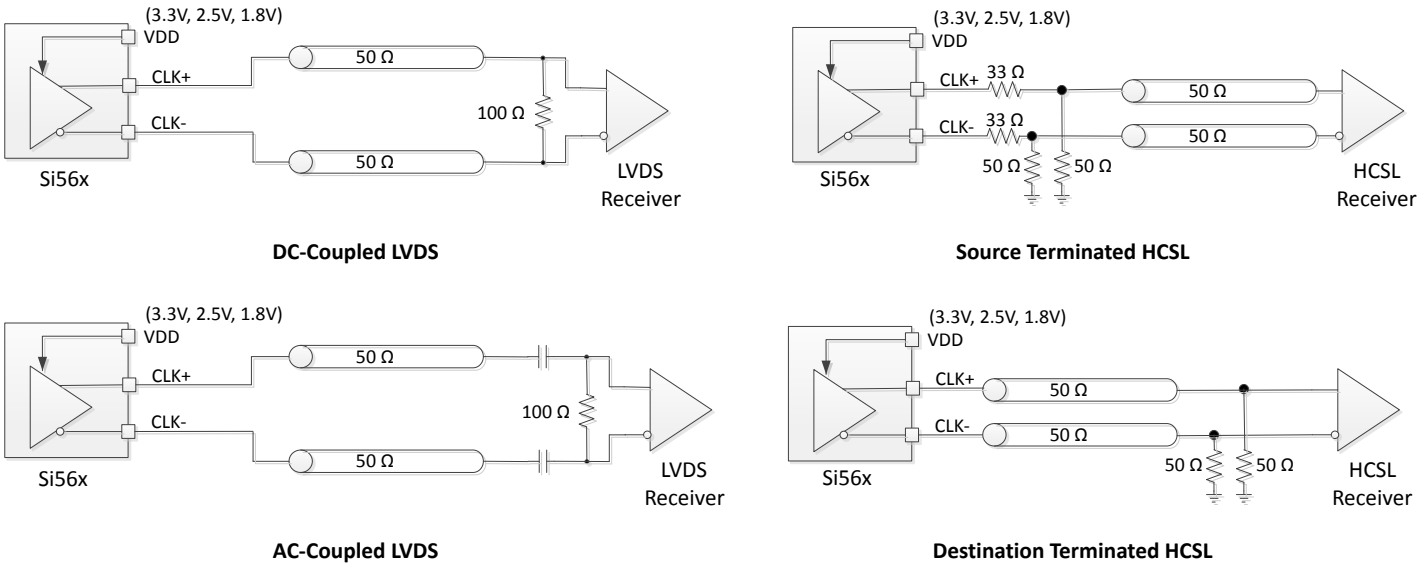


Figure 4.2. LVDS and HCSL Output Terminations

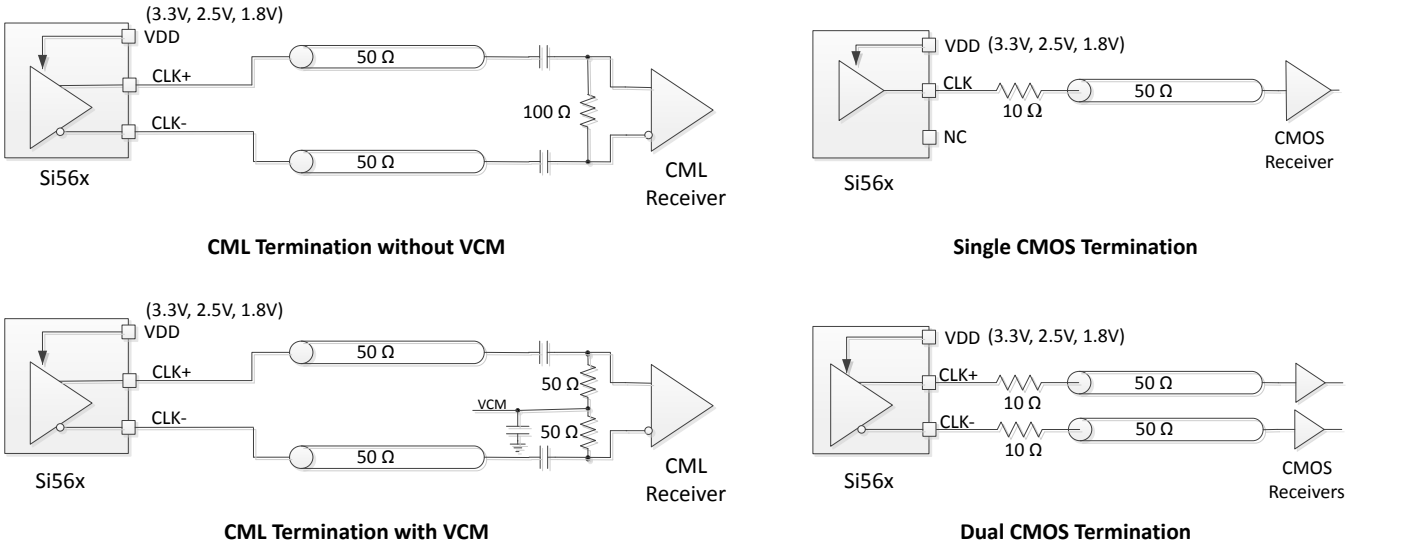


Figure 4.3. CML and CMOS Output Terminations

5. Package Outline

5.1 Package Outline (5×7 mm)

The figure below illustrates the package details for the 5×7 mm Si560. The table below lists the values for the dimensions shown in the illustration.

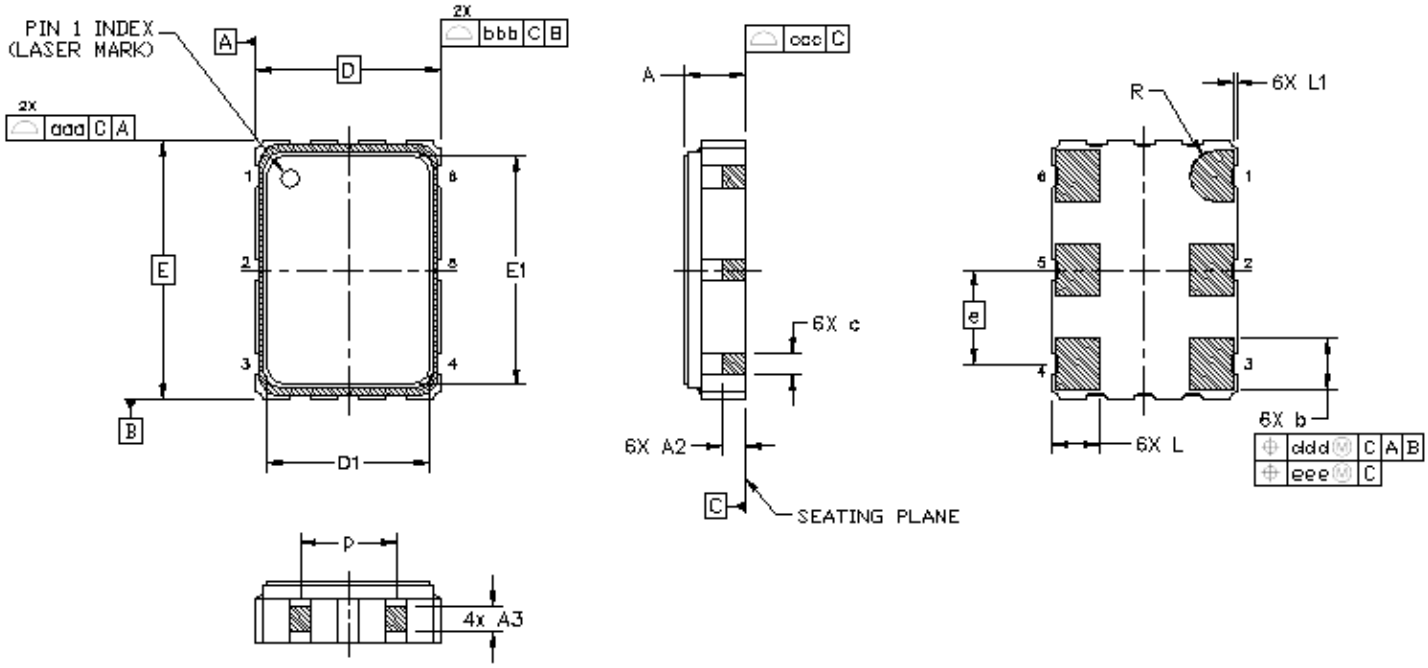


Figure 5.1. Si560 (5×7 mm) Outline Diagram

Table 5.1. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max		Dimension	Min	Nom	Max
A	1.13	1.28	1.43		L	1.17	1.27	1.37
A2	0.50	0.55	0.60		L1	0.05	0.10	0.15
A3	0.50	0.55	0.60		p	1.70	—	1.90
b	1.30	1.40	1.50		R	0.70 REF		
c	0.50	0.60	0.70		aaa	0.15		
D	5.00 BSC				bbb	0.15		
D1	4.30	4.40	4.50		ccc	0.08		
e	2.54 BSC				ddd	0.10		
E	7.00 BSC				eee	0.05		
E1	6.10	6.20	6.30					

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.2 Package Outline (3.2×5 mm)

The figure below illustrates the package details for the 3.2×5 mm Si560. The table below lists the values for the dimensions shown in the illustration.

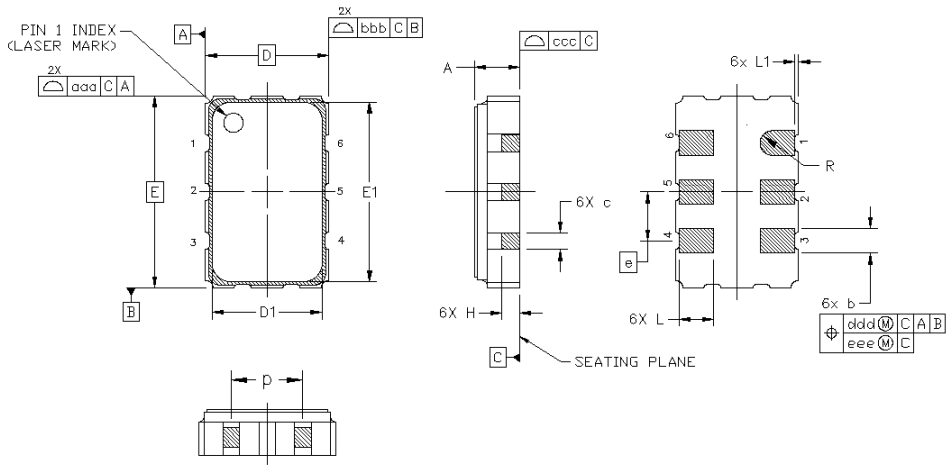


Figure 5.2. Si560 (3.2×5 mm) Outline Diagram

Table 5.2. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	1.06	1.17	1.33
b	0.54	0.64	0.74
c	0.35	0.45	0.55
D		3.20 BSC	
D1	2.55	2.60	2.65
e		1.27 BSC	
E		5.00 BSC	
E1	4.35	4.40	4.45
H	0.45	0.55	0.65
L	0.80	0.90	1.00
L1	0.05	0.10	0.15
p	1.36	1.46	1.56
R		0.32 REF	
aaa		0.15	
bbb		0.15	
ccc		0.08	
ddd		0.10	
eee		0.05	

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.3 Package Outline (2.5x3.2 mm)

The figure below illustrates the package details for the 2.5x3.2 mm Si560. The table below lists the values for the dimensions shown in the illustration.

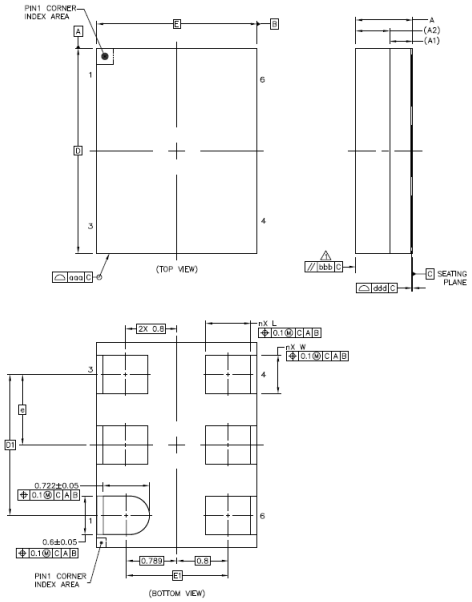


Figure 5.3. Si560 (2.5×3.2 mm) Outline Diagram

Table 5.3. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	0.90	0.95	1.00
A1		0.36 REF	
A2		0.53 REF	
W	0.55	0.60	0.65
D		3.2 BSC	
E		2.5 BSC	
e		1.10 BSC	
L	0.65	0.70	0.75
n		5	
D1		2.2 BSC	
E1		1.589 BSC	
aaa		0.10	
bbb		0.10	
ddd		0.08	

Notes:

1. The dimensions in parentheses are reference.
2. All dimensions in millimeters (mm).
3. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

6. PCB Land Pattern

6.1 PCB Land Pattern (5×7 mm)

The figure below illustrates the 5×7 mm PCB land pattern for the Si560. The table below lists the values for the dimensions shown in the illustration.

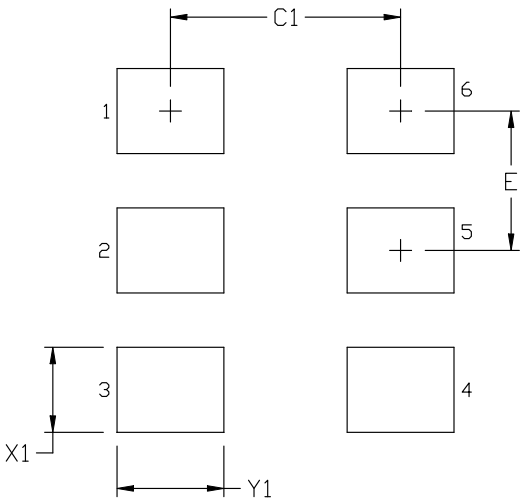


Figure 6.1. Si560 (5×7 mm) PCB Land Pattern

Table 6.1. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	4.20
E	2.54
X1	1.55
Y1	1.95

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.2 PCB Land Pattern (3.2×5 mm)

The figure below illustrates the 3.2×5.0 mm PCB land pattern for the Si560. The table below lists the values for the dimensions shown in the illustration.

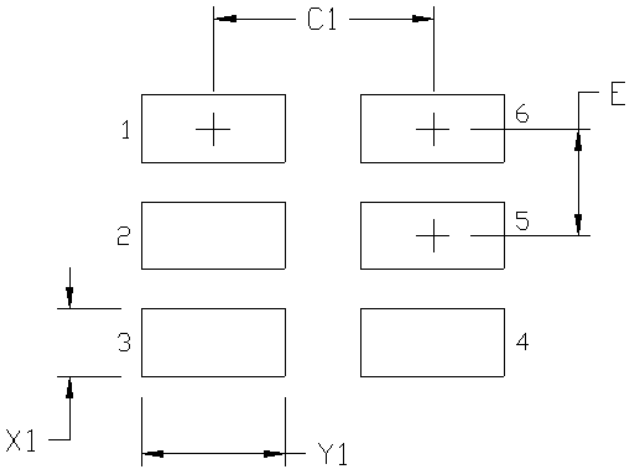


Figure 6.2. Si560 (3.2×5 mm) PCB Land Pattern

Table 6.2. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	2.60
E	1.27
X1	0.80
Y1	1.70

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.3 PCB Land Pattern (2.5×3.2 mm)

The figure below illustrates the 2.5×3.2 mm PCB land pattern for the Si560. The table below lists the values for the dimensions shown in the illustration.

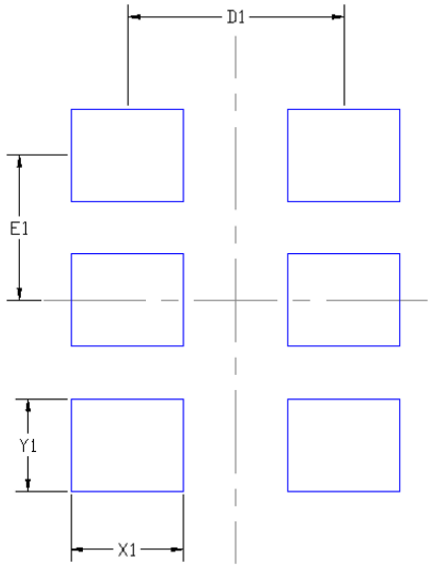


Figure 6.3. Si560 (2.5×3.2 mm) PCB Land Pattern

Table 6.3. PCB Land Pattern Dimensions (mm)

Dimension	Description	Value (mm)
X1	Width - leads on long sides	0.85
Y1	Height - leads on long sides	0.7
D1	Pitch in X directions of XLY1 leads	1.639
E1	Lead pitch XLY1 leads	1.10

Notes: The following notes and stencil design are shared as recommendations only. A customer or user may find it necessary to use different parameters and fine-tune their SMT process as required for their application and tooling.

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 0.8:1 for the pads.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

7. Top Markings

7.1 Top Marking (5x7 and 3.2x5 mm Package)

The figure below illustrates the mark specification for the Si560 5x7 and 3.2x5 package sizes. The table below lists the line information.

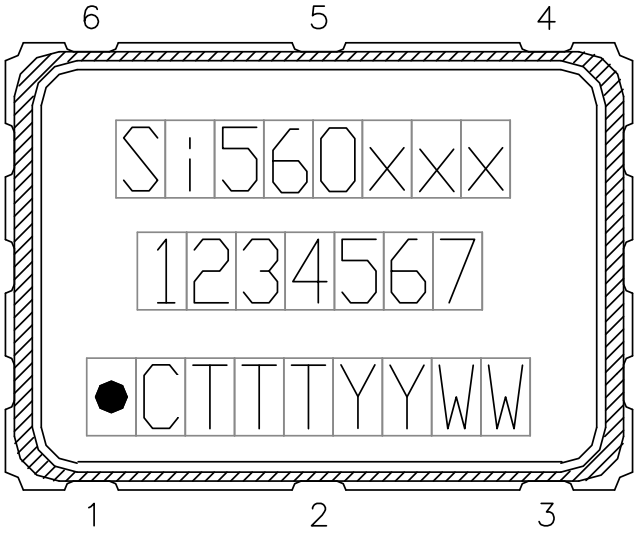


Figure 7.1. Mark Specification

Table 7.1. Si560 Top Mark Description

Line	Position	Description
1	1–8	"Si560", xxx = Ordering Option 1, Option 2, Option 3 (e.g. Si560AAA)
2	1–7	Frequency Code (e.g. 100M000 or 6-digit custom code as described in the Ordering Guide)
3	**Trace Code**	
	Position 1	Pin 1 orientation mark (dot)
	Position 2	Product Revision (C)
	Position 3–5	Tiny Trace Code (3 alphanumeric characters per assembly release instructions)
	Position 6–7	Year (last two digits of the year), to be assigned by assembly site (ex: 2017 = 17)
	Position 8–9	Calendar Work Week number (1–53), to be assigned by assembly site

7.2 Top Marking (2.5x3.2 Package)

The figure below illustrates the mark specification for the Si560 2.5x3.2 package sizes. The table below lists the line information.

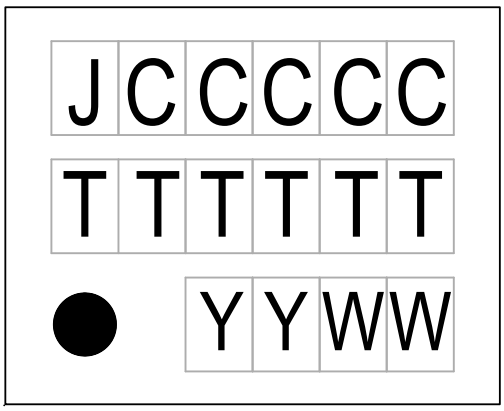


Figure 7.2. Mark Specification

Table 7.2. Si560 Top Mark Description

Line	Position	Description
1	1–6	J = Si560, CCCCC = Custom Mark Code.
2	**Trace Code**	
	1–6	Six-digit trace code per assembly release instructions.
3	Position 1	Pin 1 orientation mark (dot).
	Position 2–3	Year (last two digits of the year), to be assigned by assembly site (e.g., 2017 = 17).
	Position 4–5	Calendar Work Week number (1–53), to be assigned by assembly site.

8. Revision History

Revision 1.3

June, 2021

- Updated Ordering Guide and Top Mark for Rev C silicon.
- Added HCSL-Fast (faster t_R/t_F) ordering option.
- Updated Table 2.1, Powerup VDD Ramp Rate.

Revision 1.2

September, 2020

- Added 2.5 x 3.2 mm package option.
- Updated Table 2.1, Powerup VDD Ramp Rate and LVDS Swing.

Revision 1.1

July, 2020

- Added 2.5 x 3.2 mm package option.

Revision 1.0

June, 2018

- Initial release.

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